

Diagonal 8.8 mm (Type 1/1.8) CMOS solid-state Image Sensor with Square Pixel for Monochrome Cameras

Description

The IMX567-AAMJ is a diagonal 8.8 mm (Type 1/1.8) CMOS active pixel type solid-state image sensor with a square pixel array and 5.10 M effective pixels. This chip features a global shutter with variable charge-integration time. This chip operates with analog 3.3 V, 2.9 V, digital 1.1 V, and interface 1.8 V quadruple power supply. High sensitivity and low dark current characteristics are achieved.

(Applications: FA cameras, ITS cameras)

Features

- ◆ CMOS active pixel type dots
- ◆ Built-in timing adjustment circuit, H/V driver and serial communication circuit
- ◆ Global shutter function
- ◆ Input frequency 37.125 MHz / 74.25 MHz / 54 MHz
- ◆ Number of recommended recording pixels: 2448 (H) × 2048 (V) approx. 5.01 M pixels
- ◆ Readout mode
 - All-pixel scan mode
 - Vertical / Horizontal 1/2 Subsampling mode
 - 2 × 2 FD binning mode
 - ROI mode
 - Vertical / Horizontal - Normal / Inverted readout mode
- ◆ Readout rate
 - Maximum frame rate in
 - All-pixel scan mode: 8 bit 96.2 frame/s, 10 bit 79.1 frame/s, 12 bit 67.2 frame/s
- ◆ Pulse Output Function
 - The monitor output for Exposure period
 - Programmable pulse output
- ◆ 8-bit / 10-bit / 12-bit A/D converter
- ◆ CDS / PGA function
 - 0 dB to 24 dB: Analog Gain (0.1 dB step)
 - 24.1 dB to 48 dB: Analog Gain: 24 dB + Digital Gain: 0.1 dB to 24 dB (0.1 dB step)
- ◆ I/O interface
 - CSI-2 serial data output (2 Lane / 4 Lane) (1188 / 891 / 594 Mbps per ch)
- ◆ Recommended lens F number: 2.8 or more (Close side)

Pregius S

* Pregius S is a registered trademark or trademark of Sony Group Corporation or its affiliates. Pregius S is a global shutter sensor technology for active pixel-type CMOS image sensors. By stacking the signal processing on the back illuminated type CMOS Image Sensor it realizes small chip size and high sensitivity, whilst using the high picture quality global shutter pixel technology of Pregius.

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Device Structure

◆ CMOS image sensor		
◆ Image size	Diagonal 8.8 mm (Type 1/1.8)	Approx. 5.10 M pixels
◆ Total number of pixels	2472 (H) × 2128 (V)	Approx. 5.26 M pixels
◆ Number of effective pixels	2472 (H) × 2064 (V)	Approx. 5.10 M pixels
◆ Number of active pixels	2472 (H) × 2064 (V)	Approx. 5.10 M pixels
◆ Number of recommended recording pixels	2448 (H) × 2048 (V)	Approx. 5.01 M pixels
◆ Unit cell size	2.74 μm (H) × 2.74 μm (V)	
◆ Optical black	Horizontal (H) direction: Front 0 pixel, rear 0 pixel Vertical (V) direction: Front 64 pixels, rear 0 pixel	
◆ Package	230 pin LGA	20.0 mm (H) × 16.8 mm (V)

Image Sensor Characteristics

(T_j = 60 °C)

Item		Value	Remarks
Sensitivity	Typ.	14510 Digit/lx/s	
Saturation signal	Min.	4094 Digit	

Basic Drive Mode

Drive mode	Recommended number of recording pixels	Maximum frame rate [frame/s]	Output interface	ADC [bit]
All pixel	2448 (H) × 2048 (V) approx. 5.01 M pixels	96	CSI-2	8
		79	CSI-2	10
		67	CSI-2	12
Vertical / Horizontal 1/2 subsampling	1224 (H) × 1024 (V) approx. 1.25 M pixels	316	CSI-2	8
		268	CSI-2	10
		232	CSI-2	12
2 × 2 FD binning mode	1224 (H) × 1024 (V) approx. 1.25 M pixels	316	CSI-2	8
		268	CSI-2	10
		232	CSI-2	12

